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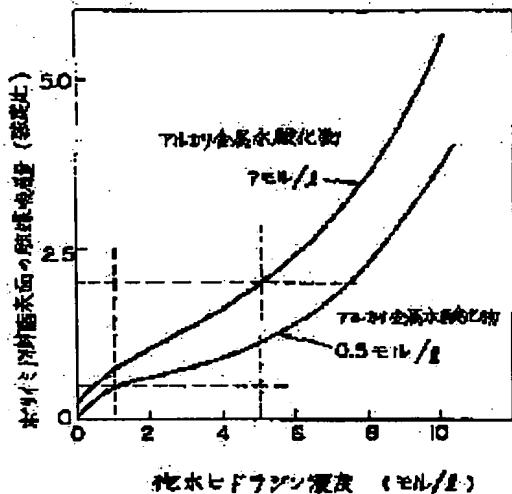
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## (54) PRODUCTION OF METAL COATED POLYIMIDE BOARD

### (57)Abstract:

**PURPOSE:** To obtain a metal coated polyimide board in which short circuit is reduced by preventing abnormal deposition of gold, or the like, at the root of wiring part when electroplating of gold is performed after formation of copper wiring part by a subtractive method or a semi-additive method.

**CONSTITUTION:** A polyimide resin film is subjected, at least on one surface thereof, to hydrophilic treatment with aqueous solution containing hydrazine and alkaline metal hydroxide and catalyst for electroless plating is imparted thus forming nickel, cobalt or an alloy thereof by electroless plating. It is then heat treated in an inert atmosphere and when a metal coated polyimide board is produced by forming a copper layer through electroless plating or electroplating of copper, the polyimide resin film is subjected to hydrophilic treatment with aqueous solution of 10–50°C containing 1–5mol/\$1 of hydrazine hydrate and 0.5–7mol/\$1 of alkaline metal hydroxide.



## LEGAL STATUS

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